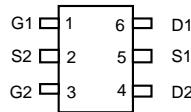
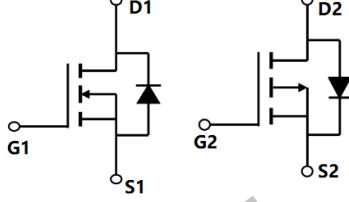
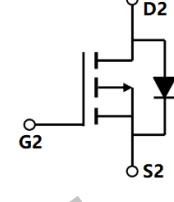


TM04G03MI6

N+P-Channel Enhancement Mode Mosfet

General Description <ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant Applications <ul style="list-style-type: none"> • Load switch • PWM 	General Features <p>N Channel $V_{DS} = 30V$, $I_D = 5.6A$ $R_{DS(ON)} = 26m\Omega$(Typ.) @ $V_{GS} = 10V$</p> <p>P Channel $V_{DS} = -30V$, $I_D = -3.9A$ $R_{DS(ON)} = 52m\Omega$(Typ.) @ $V_{GS} = -10V$</p> <p>100% UIS Tested 100% R_g Tested</p> 
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 <p>Marking: 04G03</p>	 <p>MI6:SOT-23-6L</p>	 
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Absolute Maximum Ratings: ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	N-Channel	P-Channel	Units
V_{DS}	Drain-Source Voltage	30	-30	V
V_{GS}	Gate-Source Voltage	± 20	± 20	V
I_D	Continuous Drain Current- $TC=25^\circ C$	5.6	-3.9	A
	Continuous Drain Current- $TC=100^\circ C$	3.6	-2.6	
I_{DM}	300 μ s Pulsed Drain Current	21	-15	A
P_D	Power Dissipation	1.4	1.4	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +175		°C

Thermal Characteristics:

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	---	85	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case	---	50	°C/W

TM04G03MI6
N+P-Channel Enhancement Mode Mosfet
N-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

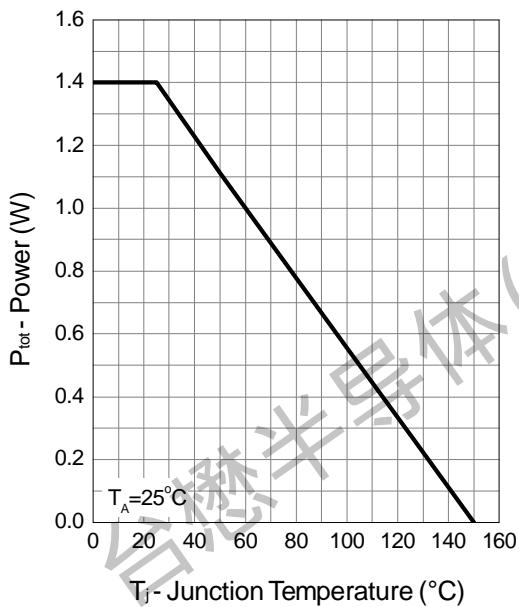
Symbol	Parameter	Test Conditions	N Channel			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_{\text{DS}}=250\mu\text{A}$	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=24\text{V}, \text{V}_{\text{GS}}=0\text{V}$ $T_J=85^{\circ}\text{C}$	-	-	1 30	μA
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_{\text{DS}}=250\mu\text{A}$	1.5	2.5	3.5	V
I_{GSS}	Gate Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	± 100	nA
$\text{R}_{\text{DS(ON)}}^{\text{a}}$	Drain-Source On-State Resistance	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_{\text{DS}}=4.9\text{A}$	-	26	35	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_{\text{DS}}=3\text{A}$	-	38	58	
Diode Characteristics						
$\text{V}_{\text{SD}}^{\text{a}}$	Diode Forward Voltage	$\text{I}_{\text{SD}}=1\text{A}, \text{V}_{\text{GS}}=0\text{V}$	-	0.75	1.1	V
t_{rr}	Reverse Recovery Time	$\text{I}_{\text{SD}}=4.9\text{A}, \frac{d\text{I}_{\text{SD}}}{dt}=100\text{A}/\mu\text{s}$	-	9.2	-	ns
Q_{rr}	Reverse Recovery Charge		-	4.3	-	nC
Dynamic Characteristics ^b						
R_g	Gate Resistance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=0\text{V}, \text{F}=1\text{MHz}$	-	2.3	-	Ω
C_{iss}	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V},$ $\text{V}_{\text{DS}}=15\text{V},$ Frequency=1.0MHz	-	215	-	pF
C_{oss}	Output Capacitance		-	37	-	
C_{rss}	Reverse Transfer Capacitance		-	28	-	
$t_{\text{d(ON)}}$	Turn-on Delay Time	$\text{V}_{\text{DD}}=15\text{V}, \text{R}_L=15\Omega,$ $\text{I}_{\text{DS}}=1\text{A}, \text{V}_{\text{GEN}}=10\text{V},$ $\text{R}_G=6\Omega$	-	5.3	8	ns
T_r	Turn-on Rise Time		-	11	16	
$t_{\text{d(OFF)}}$	Turn-off Delay Time		-	12	17	
T_f	Turn-off Fall Time		-	2.6	4	
Gate Charge Characteristics ^b						
Q_g	Total Gate Charge	$\text{V}_{\text{DS}}=15\text{V},$ $\text{I}_{\text{DS}}=4.9\text{A}$	$\text{V}_{\text{GS}}=4.5\text{V},$ $\text{V}_{\text{GS}}=10\text{V}$	-	3 5.8	-
			-	-	-	nC
Q_{gs}	Gate-Source Charge	$\text{V}_{\text{DS}}=15\text{V}, \text{V}_{\text{GS}}=10\text{V},$ $\text{I}_{\text{DS}}=4.9\text{A}$	-	1.1	-	
Q_{gd}	Gate-Drain Charge		-	1.5	-	
Q_{gth}	Threshold Gate Charge		-	0.5	-	

TM04G03MI6
N+P-Channel Enhancement Mode Mosfet
P-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

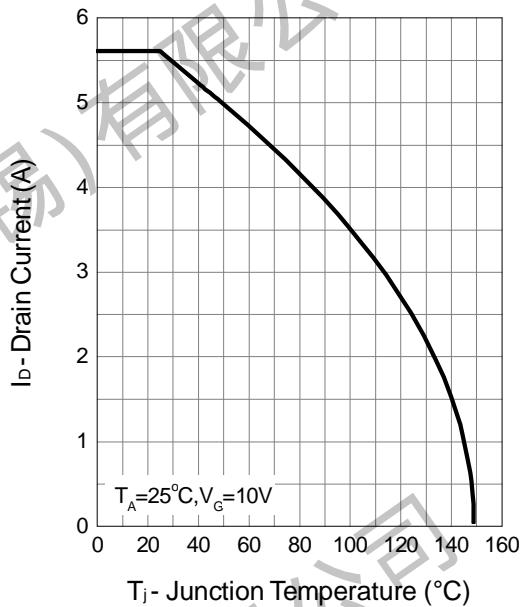
Symbol	Parameter	Test Conditions	P Channel			Unit	
			Min.	Typ.	Max.		
Static Characteristics							
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_{\text{DS}}=-250\mu\text{A}$	-30	-	-	V	
I_{DSS}	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=-24\text{V}, \text{V}_{\text{GS}}=0\text{V}$ $T_J=85^{\circ}\text{C}$	-	-	-1	μA	
			-	-	-30		
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_{\text{DS}}=-250\mu\text{A}$	-1.5	-2.5	-3.5	V	
I_{GSS}	Gate Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	± 100	nA	
$\text{R}_{\text{DS(ON)}}^{\text{a}}$	Drain-Source On-State Resistance	$\text{V}_{\text{GS}}=-10\text{V}, \text{I}_{\text{DS}}=-3\text{A}$	-	52	62	$\text{m}\Omega$	
		$\text{V}_{\text{GS}}=-4.5\text{V}, \text{I}_{\text{DS}}=-1.9\text{A}$	-	65	88		
Diode Characteristics							
$\text{V}_{\text{SD}}^{\text{a}}$	Diode Forward Voltage	$\text{I}_{\text{SD}}=-1\text{A}, \text{V}_{\text{GS}}=0\text{V}$	-	-0.75	-1.1	V	
t_{rr}	Reverse Recovery Time	$\text{I}_{\text{SD}}=-3\text{A}, \frac{d\text{I}_{\text{SD}}}{dt}=100\text{A}/\mu\text{s}$	-	19	-	ns	
Q_{rr}	Reverse Recovery Charge		-	14	-	nC	
Dynamic Characteristics ^b							
R_g	Gate Resistance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=0\text{V}, \text{F}=1\text{MHz}$	-	7	-	Ω	
C_{iss}	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=-15\text{V}, \text{Frequency}=1.0\text{MHz}$	-	229	-	pF	
C_{oss}	Output Capacitance		-	42	-		
C_{rss}	Reverse Transfer Capacitance		-	33	-		
$\text{t}_{\text{d(ON)}}$	Turn-on Delay Time	$\text{V}_{\text{DD}}=-15\text{V}, \text{R}_L=15\Omega, \text{I}_{\text{DS}}=-1\text{A}, \text{V}_{\text{GEN}}=-10\text{V}, \text{R}_G=6\Omega$	-	7.2	-	ns	
T_r	Turn-on Rise Time		-	9.3	-		
$\text{t}_{\text{d(OFF)}}$	Turn-off Delay Time		-	15.4	-		
T_f	Turn-off Fall Time		-	3.6	-		
Gate Charge Characteristics ^b							
Q_g	Total Gate Charge	$\text{V}_{\text{DS}}=-15\text{V}, \text{I}_{\text{DS}}=-3\text{A}$	$\text{V}_{\text{GS}}=-4.5\text{V},$	-	3.3	-	nC
			$\text{V}_{\text{GS}}=-10\text{V}$	-	6.5	-	
Q_{gs}	Gate-Source Charge	$\text{V}_{\text{DS}}=-15\text{V}, \text{V}_{\text{GS}}=-10\text{V}, \text{I}_{\text{DS}}=-3\text{A}$	-	1.1	-	nC	
Q_{gd}	Gate-Drain Charge		-	1.1	-		
Q_{gth}	Threshold Gate Charge		-	0.6	-		

N-Channel Typical Characteristics

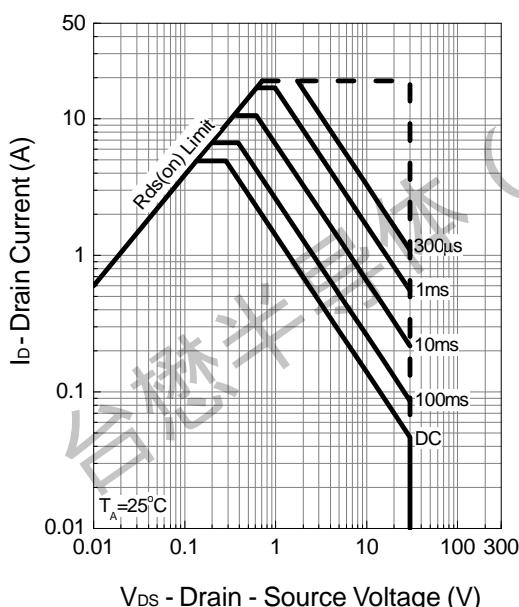
Power Dissipation



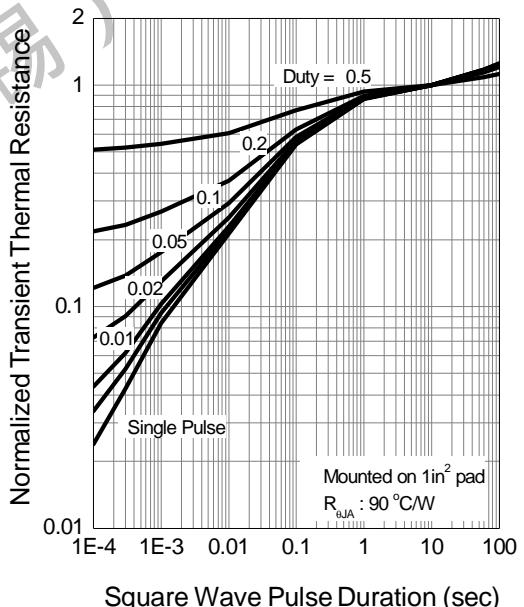
Drain Current

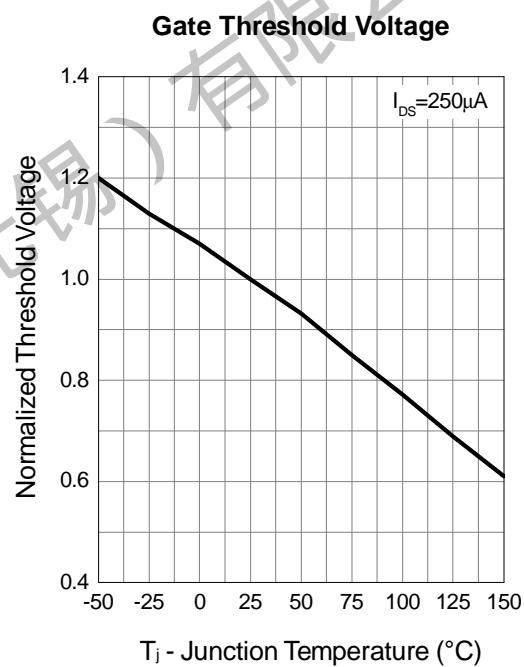
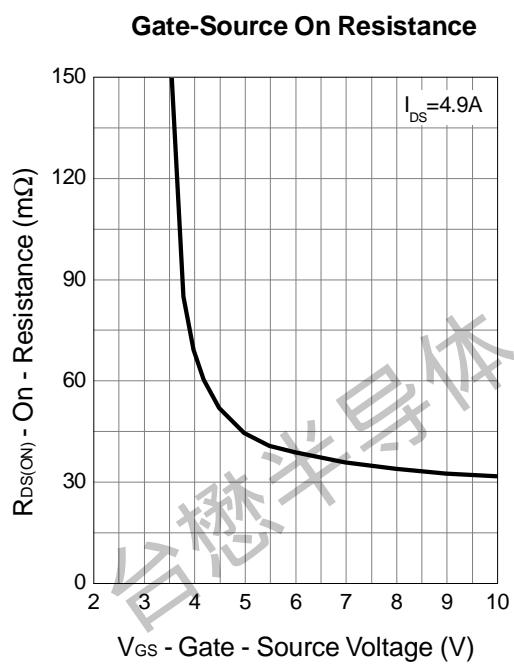
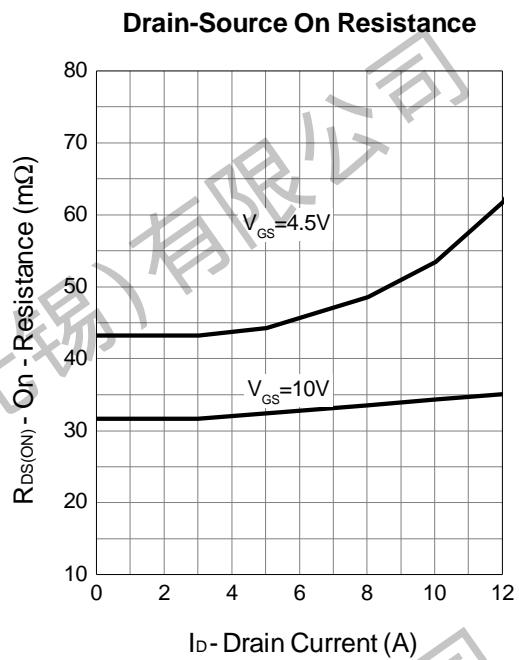
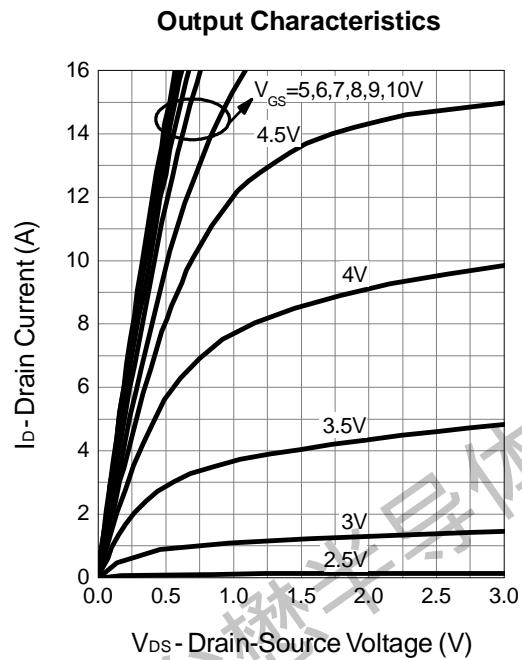


Safe Operation Area



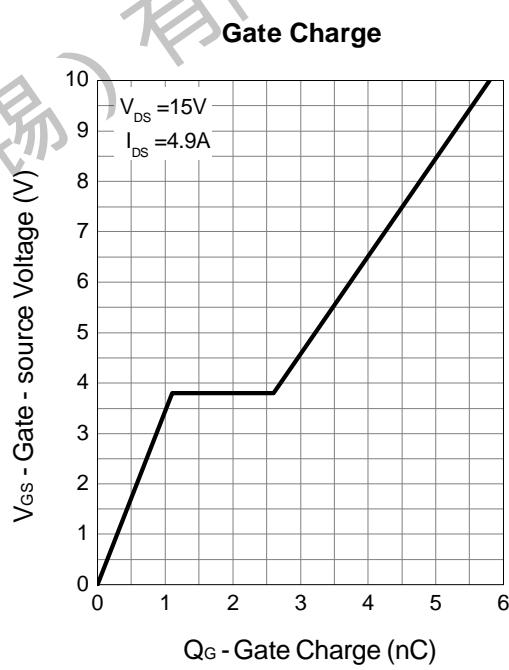
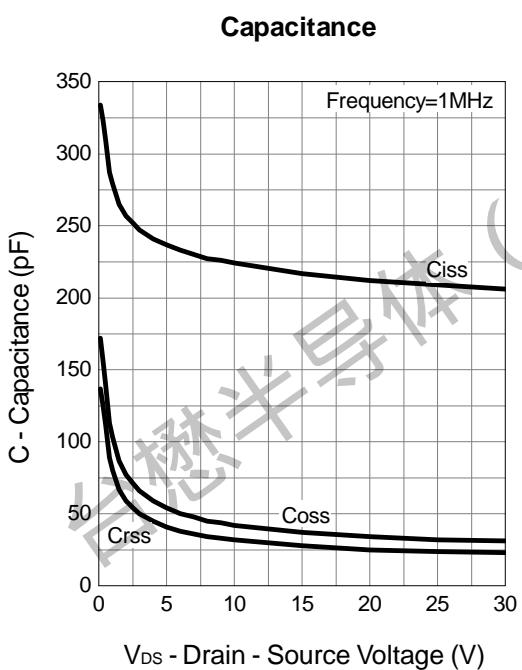
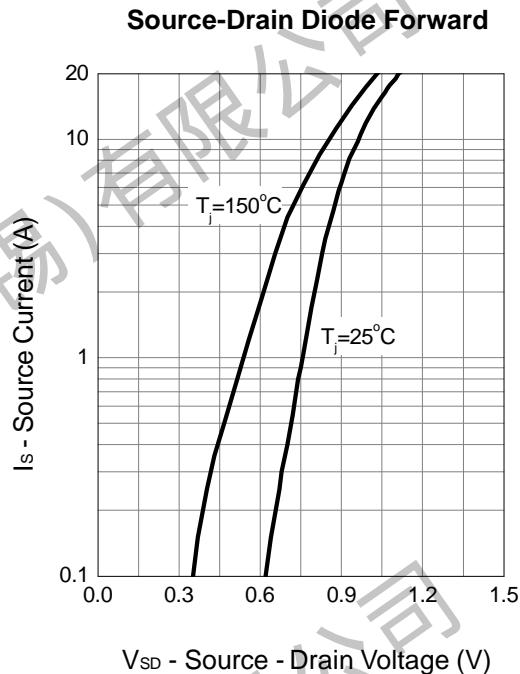
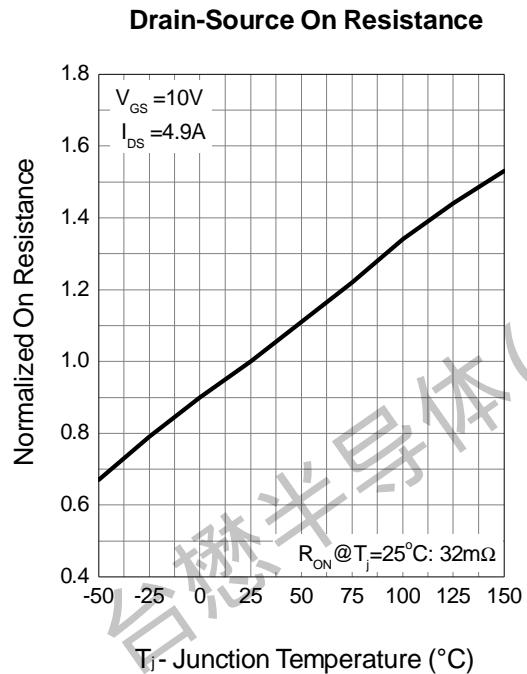
Thermal Transient Impedance



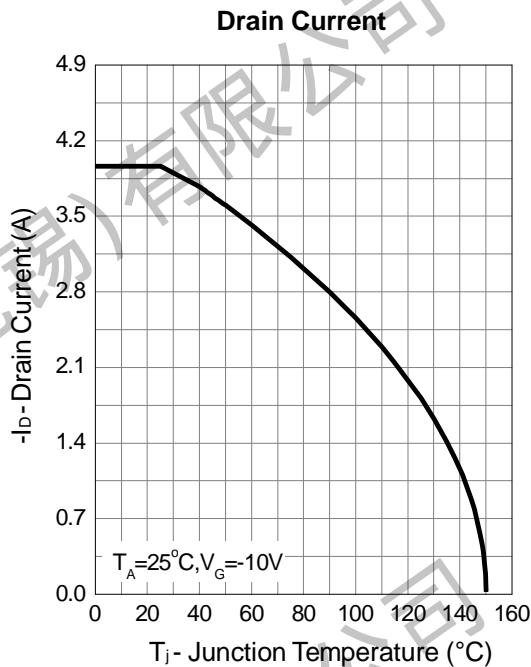
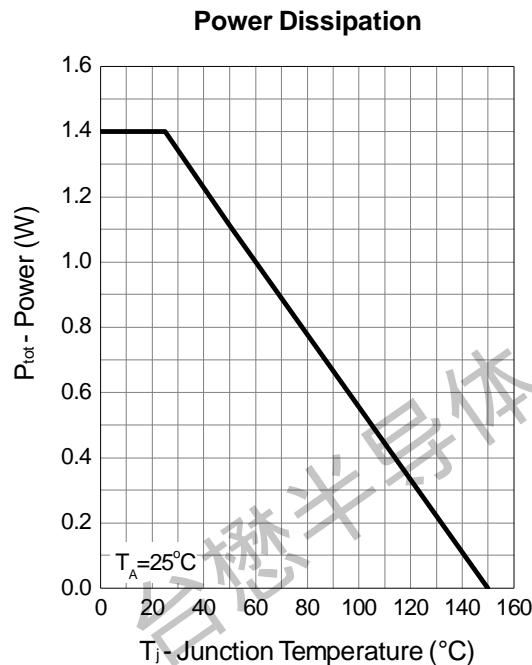


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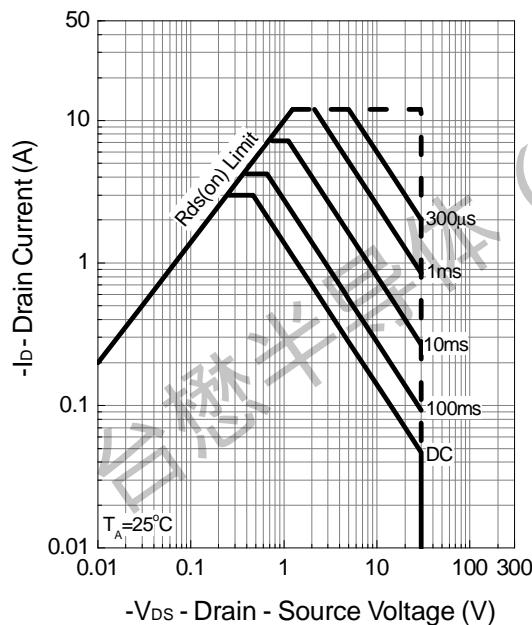
N+P-Channel Enhancement Mode Mosfet



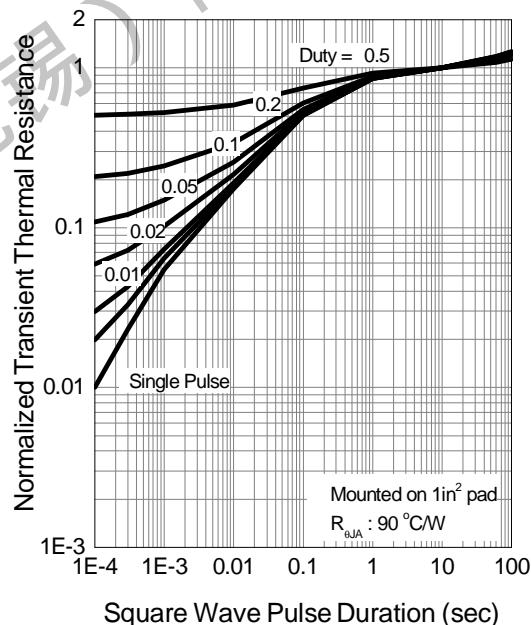
P-Typical Characteristics



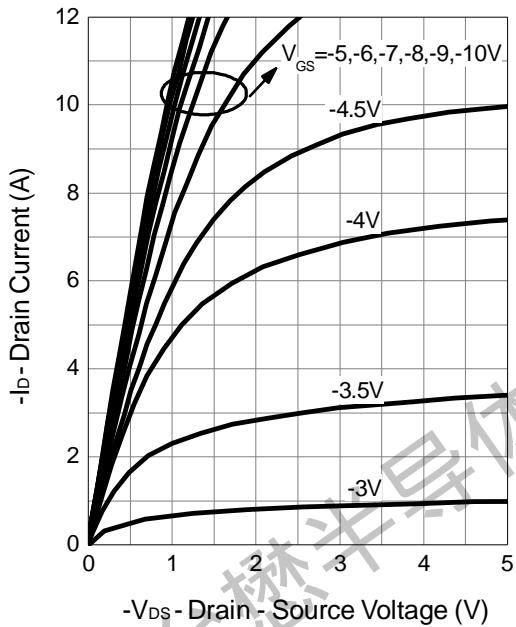
Safe Operation Area



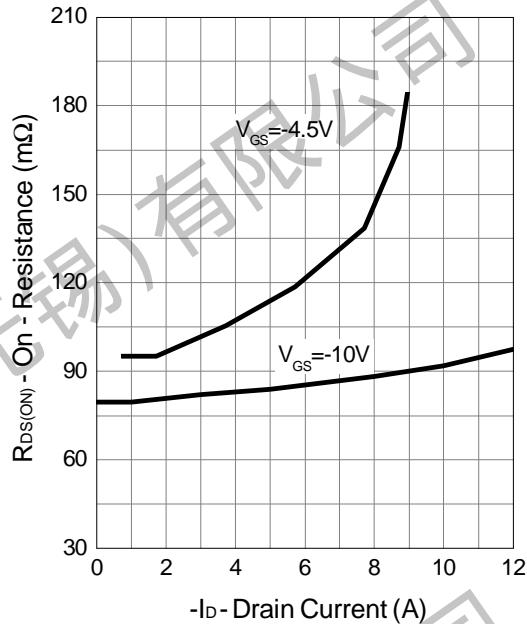
Thermal Transient Impedance



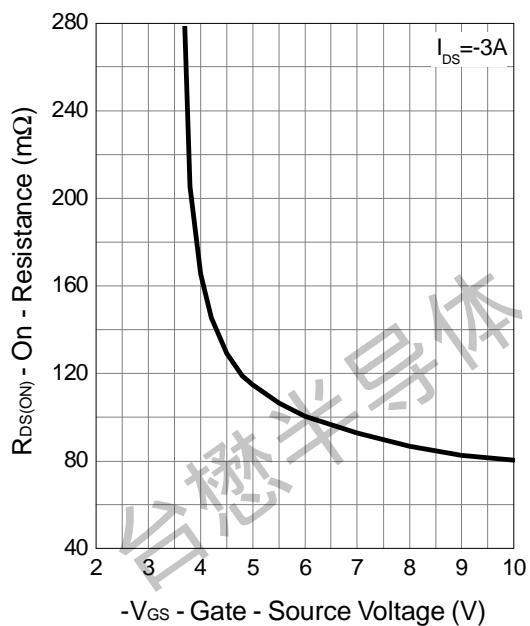
Output Characteristics



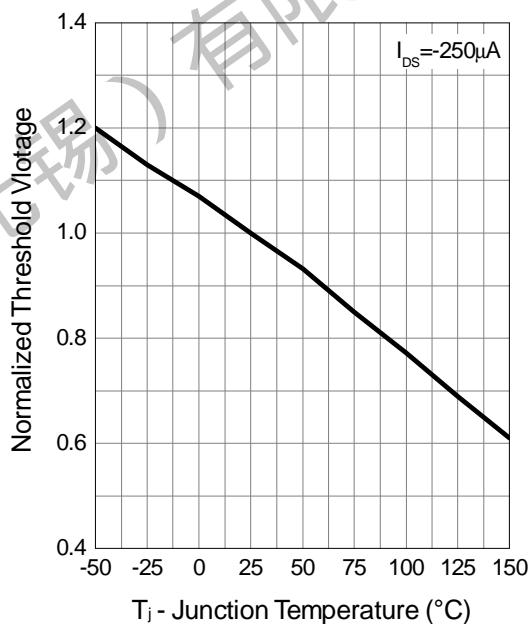
Drain-Source On Resistance

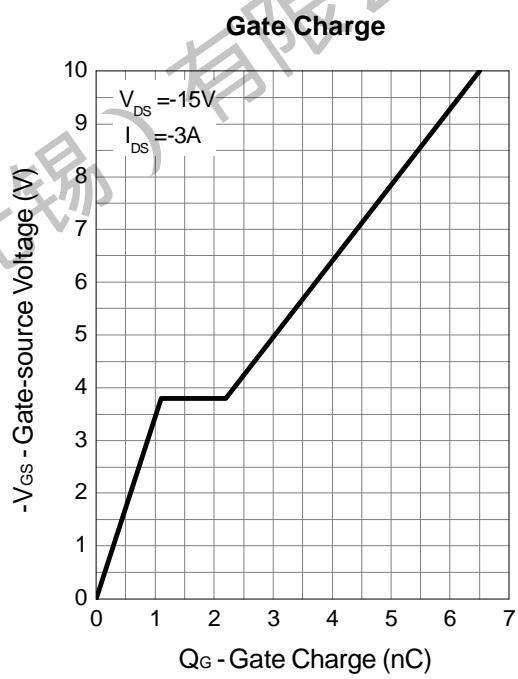
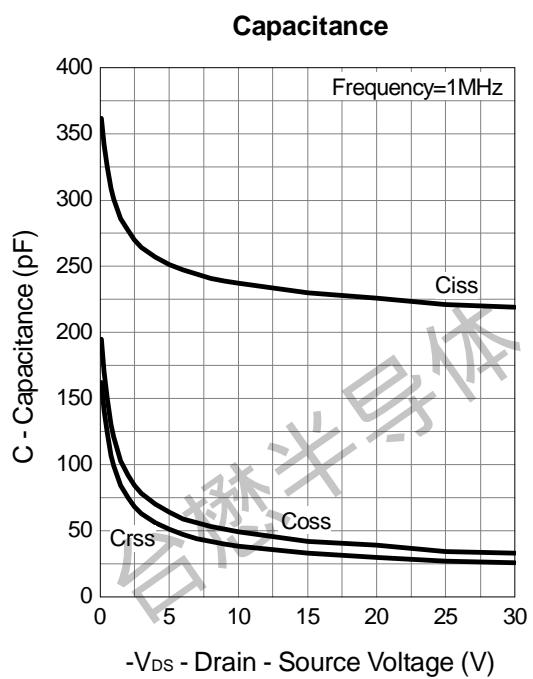
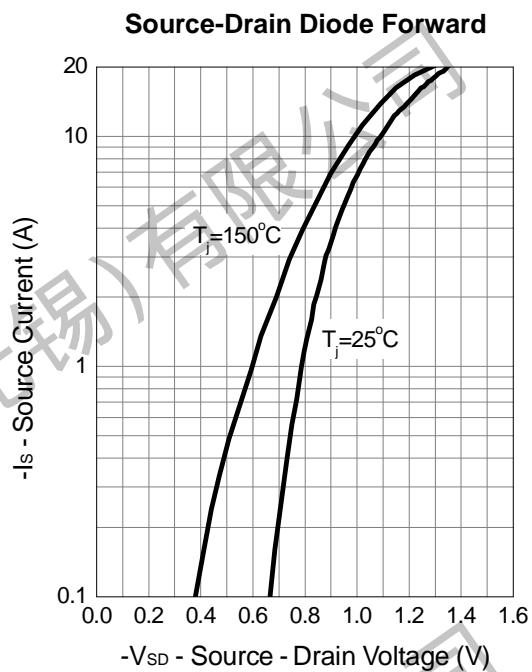
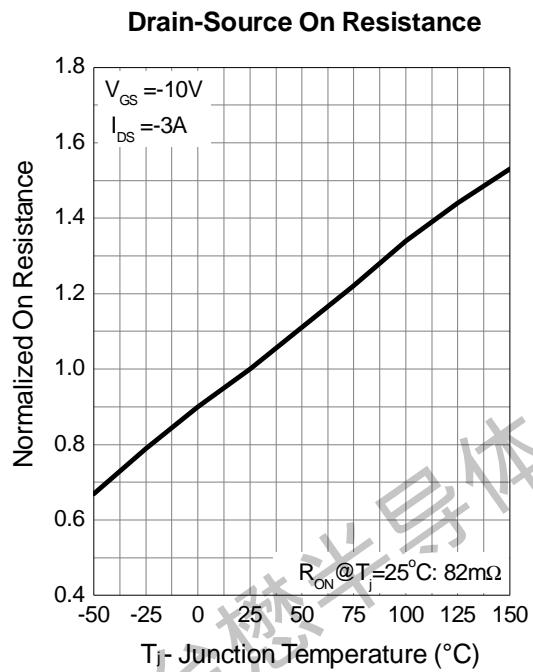


Gate-Source On Resistance



Gate Threshold Voltage

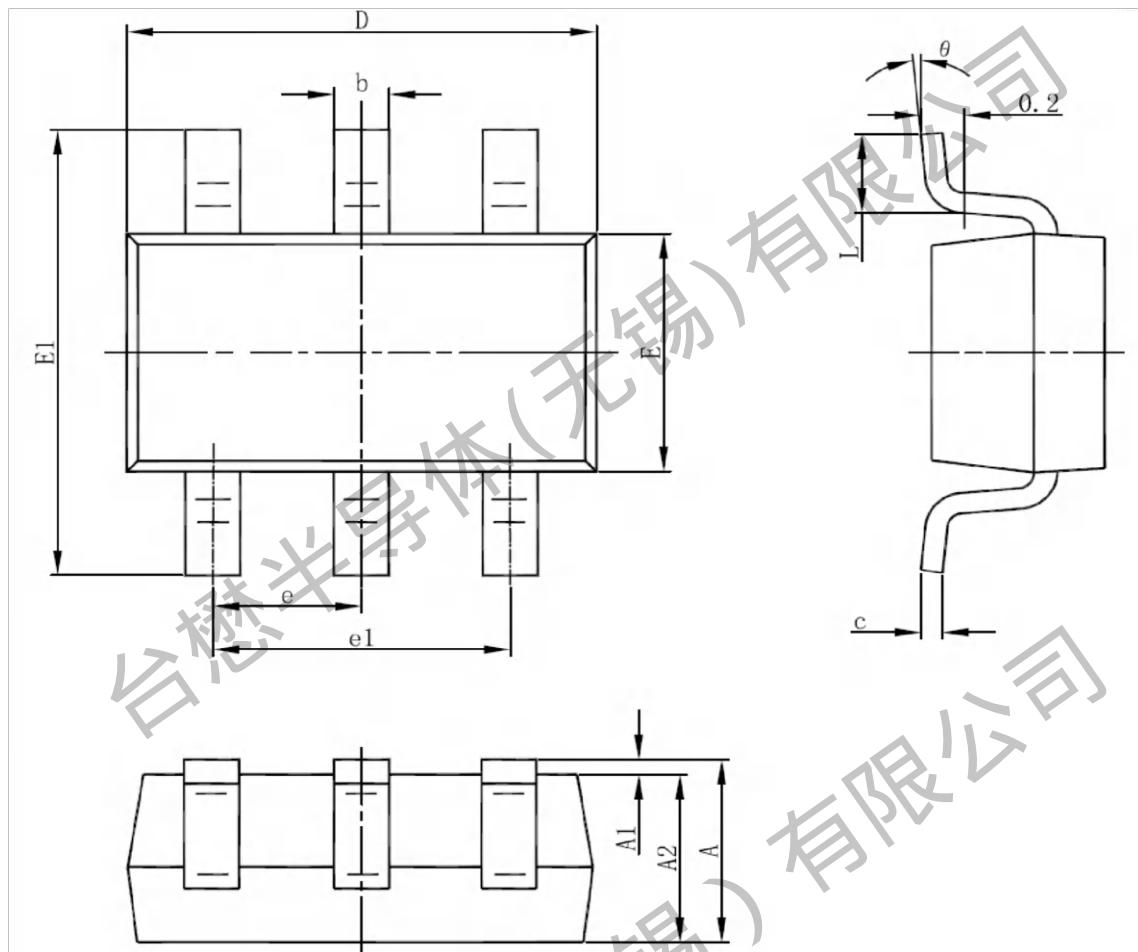




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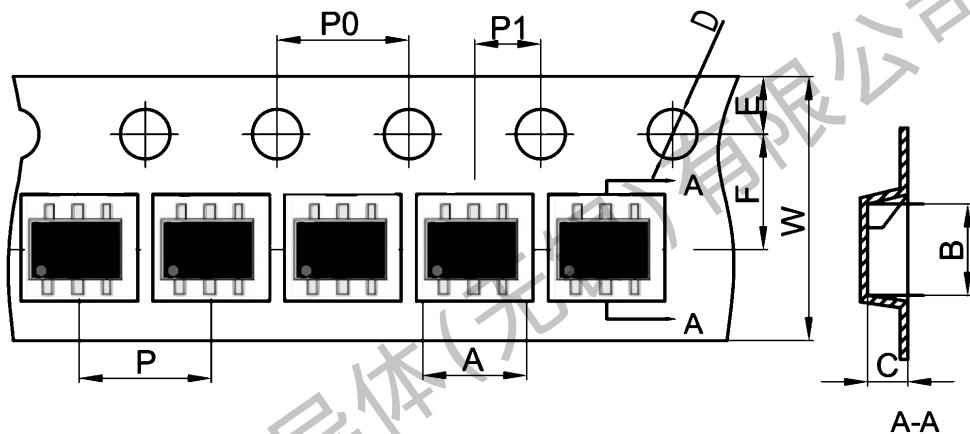
N+P-Channel Enhancement Mode Mosfet

Package Mechanical Data :SOT-23-6L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

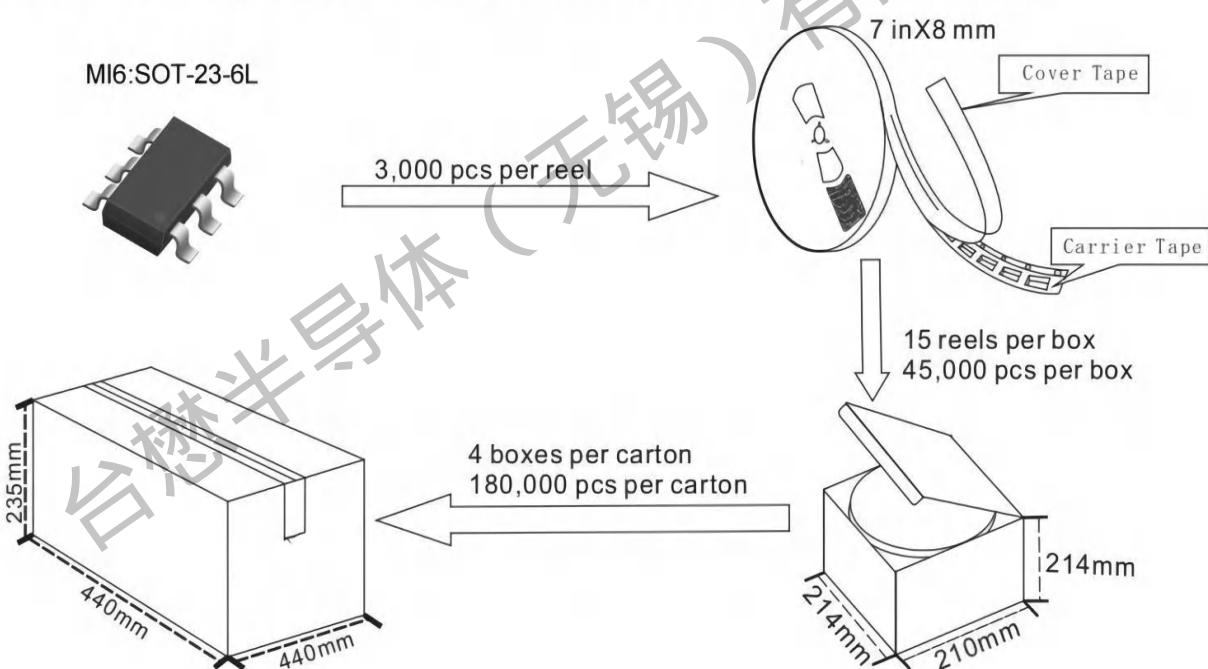
SOT-23-6L Embossed Carrier Tape



Dimensions are in millimeter									
Pkg type	A	B	C	D	E	F	P0	P	W
SOT-23-6L	3.15	2.77	1.22	Ø1.50	1.75	3.50	4.00	4.00	2.00

SOT-23-6L Packing

The method of packaging and dimension are shown as below figure. (Dimension in mm)



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Revision history:

Date	Rev	Description	Page
2023.06.22	23.06	Original	